



Sample &

Buy





TWL6040

SWCS052B-AUGUST 2010-REVISED AUGUST 2014

TWL6040 8-Channel Low-Power Audio Codec for Portable Applications

Device Overview 1

INSTRUMENTS

1.1 Features

Texas

- Four Audio Digital-to-Analog Converter (DAC) Channels
- Stereo Capless Headphone Drivers:
 - Up to 104-dB DR
 - Power Tune for Performance and Power Consumption Tradeoff
- Stereo 8 Ω, 1.5 W per Channel Speaker Drivers
- **Differential Earpiece Driver**
- Stereo Line-Out
- Two Audio Analog-to-Digital Converter (ADC) Channels:
 - 96-dBA SNR
- Four Audio Inputs:
 - Three Differential Microphone Inputs
 - Stereo Line-In and FM Input
- Two Vibrator and Haptics Feedback Channels: Differential H-Bridge Drivers
- Two Low-Noise Analog Microphone Bias Outputs
- Two Digital Microphone Bias Outputs
- Analog Low-Power Loop from Line-in to Headphone and Speaker Outputs

Applications 1.2

Mobile and Smart Phones

- Dual Phase-Locked Loops (PLLs) for Flexible Clock Support:
 - 32-kHz Sleep Clock Input for System Low-Power Playback Mode
 - 12-, 19.2-, 26-, and 38.4-MHz System Clock Input
- Accessory Plug and Unplug Detection, Accessory **Button Press Detection**
- Integrated Power Supplies:
 - Negative Charge Pump for Capless Headphone Driver
 - Two Low Dropout Voltage Regulators (LDOs) for High Power Supply Rejection Ratio (PSRR)
- Thermal Protection:
 - Host Interrupt
- Power Supplies:

 - Digital I/O: 1.8 V

Handheld Devices

- Battery: 2.3 to 5.5 V
- Package 6-mm x 6-mm 120-Pin PBGA
- PRODUCT PREVIEW

- **MP3 Players**

1.3 Description

The TWL6040 device is an audio coder/decoder (codec) with a high level of integration providing analog audio codec functions for portable applications, as shown in Figure 1-1. The device contains multiple audio analog inputs and outputs, as well as microphone biases and accessory detection. The device is connected to the OMAP™ 4 host processor through a proprietary PDM interface for audio data communication enabling partitioning with optimized power consumption and performance. Multichannel audio data is multiplexed to a single wire for downlink (PDML) and uplink (PDMUL).

The OMAP4 device provides the TWL6040 device with five PDM audio-input channels (DL0-DL4). Channels DL0–DL3 are connected to four parallel DAC channels multiplexed to stereo headphone (HSL, HSR), stereo speaker (HFL, HFR), and earpiece (EAR) or stereo line outputs (AUXL, AUXR).

The stereo headphone path has a low-power (LP) mode operating from a 32-kHz sleep clock to enable more than 100 hours of MP3 playback time. Very-high dynamic range of 104 dBA is achieved when using the system clock input and DAC path high-performance (HP) mode. Class-AB headphone drivers provide a 1-V_{rms} capability output and are ground centered for capless connection to a headphone, thus enabling system size and cost reduction. The earpiece driver is a differential class-AB driver with 2 V_{rms} capability to a typical 32- Ω load or 1.4 V_{rms} to a typical 16- Ω load.



- I²C Control

- Analog: 2.1 V

Stereo speaker path has filterless class-D outputs with 1.5-W capability per channel. Output power maximization supply connections to an external boost is supported. Speaker drivers also support hearing aid coil loads. For vibrator and haptic feedback support, the TWL6040 has two PWM channels with independent input signals from DL4 or inter-integrated circuit (I^2C).

Vibrator drivers are differential H-bridge outputs, enabling fast acceleration and deceleration of vibrator motor. An external driver for a hearing aid coil or a piezo speaker requiring high voltage can be connected to line outputs.

The TWL6040 supports three differential microphone inputs (MMIC, HMIC, and SMIC) and a stereo lineinput (AFML, AFMR) multiplexed to two parallel ADCs. The PDM output from the ADCs is transmitted to the OMAP4 processor through UL0 and UL1. AFML, AFMR inputs can also be looped to analog outputs (LB0, LB1).

Two LDOs provide a voltage of 2.1 V to bias analog microphones (MBIAS and HBIAS). The maximum output current is 2 mA for each analog bias, allowing up to two microphones on one bias. Two LDOs provide a voltage of 1.8 V/1.85 V to bias digital microphones (DBIAS1 and DBIAS2). One bias generator can bias several digital microphones at the same time, with a total maximum output current of 10 mA.

The TWL6040 has an integrated negative charge pump (NCP) and two LDOs (HS LDO and LS LDO) for high PSRR. The only external supply needed is 2.1 V, which is available from the 2.1-V DC-DC of the TWL6030 power-management IC (PMIC) in the OMAP4 system. By powering audio from low-noise 2.1-V DC-DC of low power consumption, high dynamic range and high output swing at headset output are achieved. All other supply inputs can be directly connected to battery or system 1.8-V I/O.

Two integrated PLLs enable operation from a 12-, 19.2-, 26-, and 38.4-MHz system clock (MCLK) or, in LP playback mode, from a 32-kHz sleep clock (CLK32K). The frequency plan is based on a 48-kS/s audio data rate for all channels, and host processor uses sample-rate converters to interface with different sample rates (for example, 44.1 kHz). In the specific case of low-power audio playback, the TWL6040 supports the 44.1-kS/s and 48-kS/s rates. Transitions between sample rates or input clocks are seamless.

Accessory plug and unplug detections are supported (PLUGDET). Some headsets have a manual switch for submitting send/end signal to the terminal through the microphone input pin. This feature is supported by a periodic accessory button press detection to minimize current consumption in sleep mode. Detection cycle properties can be programmed according to system requirements.

Table 1-1. Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)
TWL6040A2	ZQZ (120)	6.00 mm × 6.00 mm
TWL6040A3	ZQZ (120)	6.00 mm × 6.00 mm

(1) For more information, see Section 3, Mechanical Packaging and Orderable Information.

TEXAS INSTRUMENTS www.ti.com

1.4 Functional Block Diagram



Figure 1-1 shows the system block diagram of the TWL6040 device.



3

SWCS044-001

For the complete TWL60xx data sheet (SWCS044), contact your TI sales representative.



2 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision A (January 2012) to Revision B	Page
Changed document to standard TI format	1

3 Mechanical Packaging and Orderable Information

3.1 Packaging Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.



8-Apr-2014

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
TWL6040A2ZQZ	ACTIVE	BGA MICROSTAR JUNIOR	ZQZ	120	250	Green (RoHS & no Sb/Br)	SNAGCU	Level-3-260C-168 HR	-40 to 85	TWL6040A2	Samples
TWL6040A2ZQZR	ACTIVE	BGA MICROSTAR JUNIOR	ZQZ	120	2500	Green (RoHS & no Sb/Br)	SNAGCU	Level-3-260C-168 HR	-40 to 85	TWL6040A2	Samples
TWL6040A3SRSZQZ	ACTIVE	BGA MICROSTAR JUNIOR	ZQZ	120	250	Green (RoHS & no Sb/Br)	SNAGCU	Level-3-260C-168 HR	-40 to 85	TWL6040A3	Samples
TWL6040A3SRSZQZR	ACTIVE	BGA MICROSTAR JUNIOR	ZQZ	120	2500	Green (RoHS & no Sb/Br)	SNAGCU	Level-3-260C-168 HR	-40 to 85	TWL6040A3	Samples
TWL6040A3ZQZ	ACTIVE	BGA MICROSTAR JUNIOR	ZQZ	120	250	Green (RoHS & no Sb/Br)	SNAGCU	Level-3-260C-168 HR	-40 to 85	TWL6040A3	Samples
TWL6040A3ZQZR	ACTIVE	BGA MICROSTAR JUNIOR	ZQZ	120	2500	Green (RoHS & no Sb/Br)	SNAGCU	Level-3-260C-168 HR	-40 to 85	TWL6040A3	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



www.ti.com

8-Apr-2014

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

www.ti.com

Texas Instruments

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TWL6040A2ZQZR	BGA MI CROSTA R JUNI OR	ZQZ	120	2500	330.0	16.4	6.3	6.3	1.5	12.0	16.0	Q1
TWL6040A3SRSZQZR	BGA MI CROSTA R JUNI OR	ZQZ	120	2500	330.0	16.4	6.3	6.3	1.5	12.0	16.0	Q1
TWL6040A3ZQZR	BGA MI CROSTA R JUNI OR	ZQZ	120	2500	330.0	16.4	6.3	6.3	1.5	12.0	16.0	Q1

TEXAS INSTRUMENTS

www.ti.com

PACKAGE MATERIALS INFORMATION

5-Sep-2014



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TWL6040A2ZQZR	BGA MICROSTAR JUNIOR	ZQZ	120	2500	336.6	336.6	31.8
TWL6040A3SRSZQZR	BGA MICROSTAR JUNIOR	ZQZ	120	2500	336.6	336.6	31.8
TWL6040A3ZQZR	BGA MICROSTAR JUNIOR	ZQZ	120	2500	336.6	336.6	31.8

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products		Applications	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Applications Processors	www.ti.com/omap	TI E2E Community	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconn	ectivity	

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2016, Texas Instruments Incorporated